



Microsoft Maia 200

Maia 200 Custom 2026 TSMC N3

OVERVIEW

— FP32 TFLOPS	216 GB VRAM HBM3e	7.0 TB/s Memory Bandwidth	750 W TDP
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PERFORMANCE METRICS

Precision	Peak TFLOPS	Bits	Type
FP8	5050.0	8	Standard
FP4	10100.0	4	Standard
BF16	1262.5	16	Standard

MEMORY SPECIFICATIONS

Capacity	216 GB
Type	HBM3e
Bandwidth	7.0 TB/s
Interface Width	—

POWER & EFFICIENCY

TDP	750 W
Est. Max Power	862 W
FP32 Efficiency	—
FP16 Efficiency	—

HARDWARE DETAILS

Vendor: Microsoft	Architecture: Maia 200	Process Node: TSMC N3
Form Factor: Custom	Launch Year: 2026	

INTERCONNECT

GPU-to-GPU: Ethernet scale-up (Maia AI Transport Layer) Bandwidth: 2.8 TB/s

CHIP DESIGN

Transistors: 140.0 billion